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2 6 Substitute for form 1449/PTO					Complete if Known		
(RD)sed 04/2003)					Application Number	10/743,527	
(RE)Sed 04/2003) TATRACT INFORMATION DISCLOSURE STATEMENT BY APPLICANT					Filing Date	December 22, 2003	
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					Group Art Unit	2841	
	(U.	se as many she	eis as necessary)		Examiner Name	(notyetassigned) HOA C. NGUYEN	
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Examiner	Warren MILLAND	Date	10/0/05
Signature	hoanguy	Considered	12 9 0 8

^{*}Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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